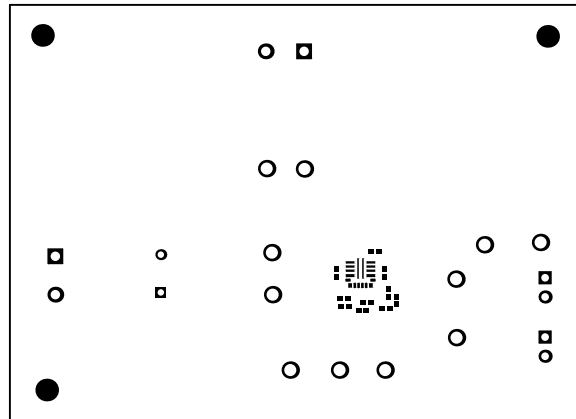
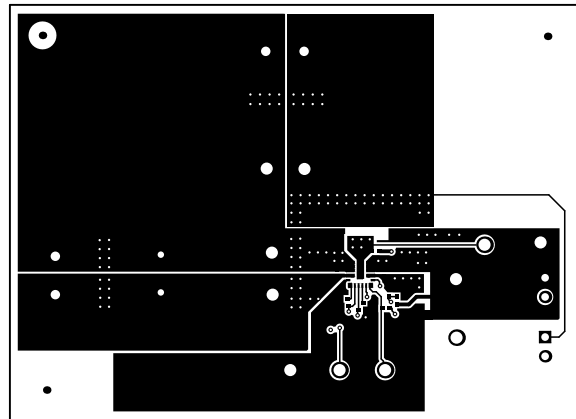


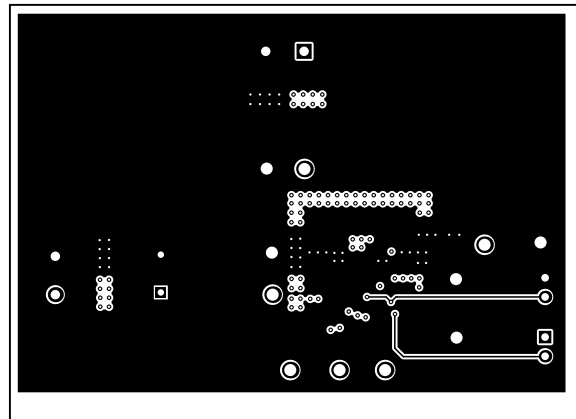
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01510	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: TIDA-01510		
PLOT NAME = Top Overlay	GENERATED : 5/29/2018 3:21:04 PM	TEXAS INSTRUMENTS	



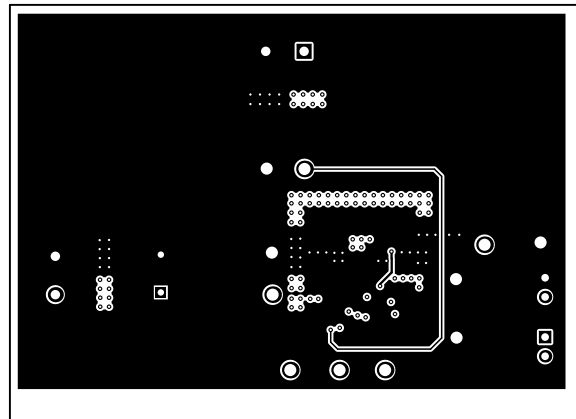
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01510	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: TIDA-01510		
PLOT NAME = Top Solder Mask	GENERATED : 5/29/2018 3:21:06 PM	TEXAS INSTRUMENTS	



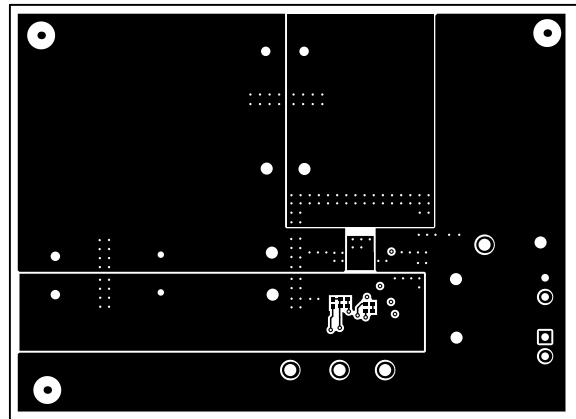
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01510	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: TIDA-01510		
PLOT NAME = Top Layer	GENERATED : 5/29/2018 3:21:07 PM	TEXAS INSTRUMENTS	



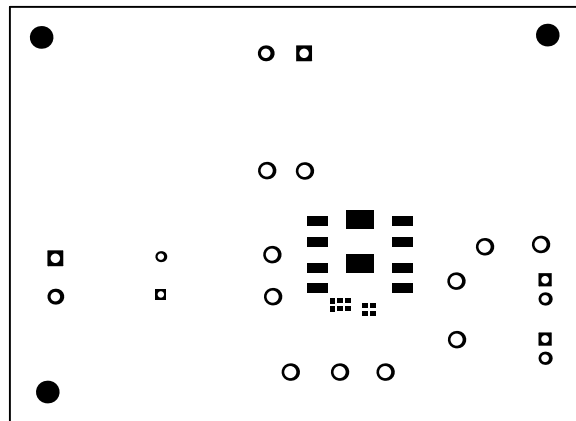
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01510	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =	TID #: TIDA-01510		
PLOT NAME = Signal Layer 1	GENERATED : 5/29/2018 3:21:09 PM	TEXAS INSTRUMENTS	



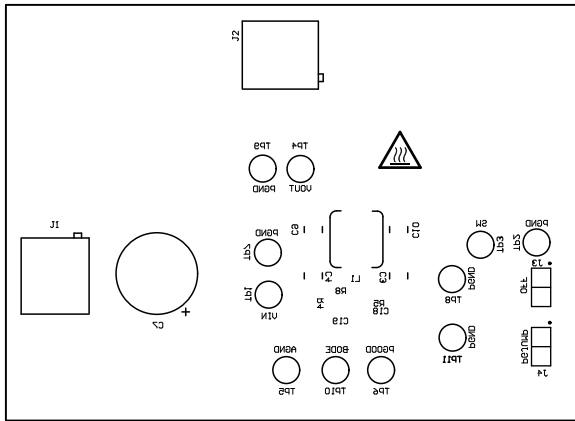
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01510	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =	TID #: TIDA-01510		
PLOT NAME = Signal Layer 2	GENERATED : 5/29/2018 3:21:10 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01510	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: TIDA-01510		
PLOT NAME = Bottom Layer	GENERATED : 5/29/2018 3:21:11 PM	TEXAS INSTRUMENTS	

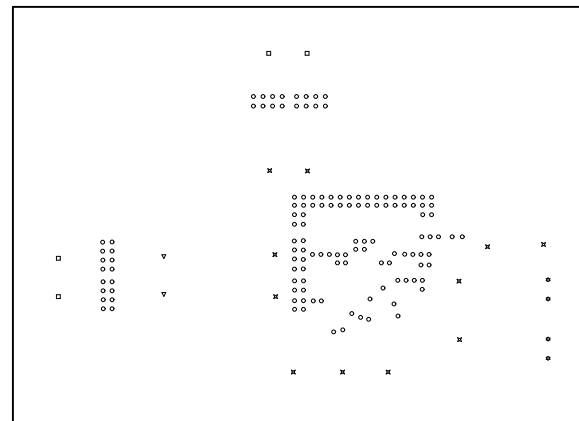


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01510	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: TIDA-01510		
PLOT NAME = Bottom Solder Mask	GENERATED : 5/29/2018 3:21:13 PM	TEXAS INSTRUMENTS	

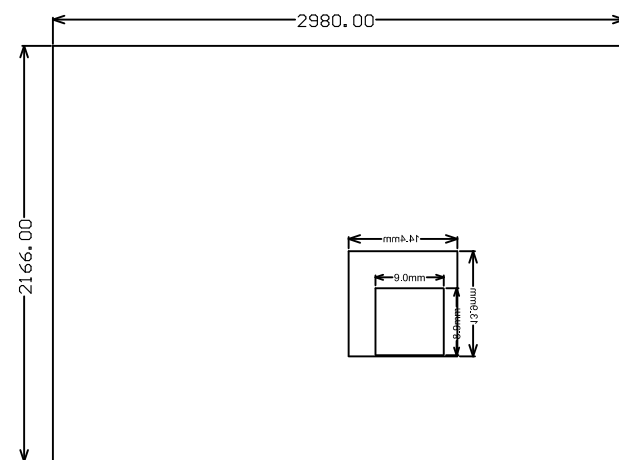


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01510	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: TIDA-01510		
PLOT NAME = Bottom Overlay	GENERATED : 5/29/2018 3:21:14 PM	TEXAS INSTRUMENTS	

Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
○	128	12.00mil (0.305mm)	PTH	Round	Top Layer - Bottom Layer	
▽	2	33.47mil (0.850mm)	PTH	Round	Top Layer - Bottom Layer	
✱	4	40.00mil (1.016mm)	PTH	Round	Top Layer - Bottom Layer	
□	4	49.21mil (1.250mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	11	63.00mil (1.600mm)	PTH	Round	Top Layer - Bottom Layer	
	149 Total					



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01510	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: TIDA-01510		
PLOT NAME = Drill Drawing	GENERATED : 5/29/2018 3:21:15 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01510	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: TIDA-01510		
PLOT NAME = Board Dimensions	GENERATED : 5/29/2018 3:21:17 PM	TEXAS INSTRUMENTS	

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